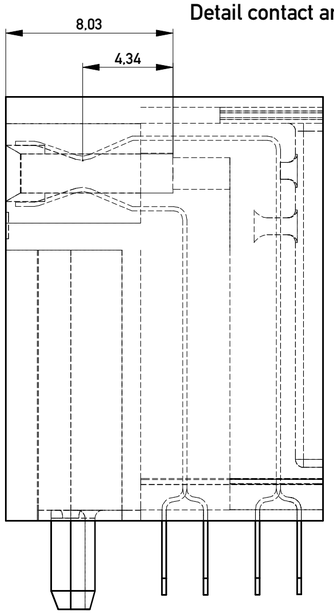
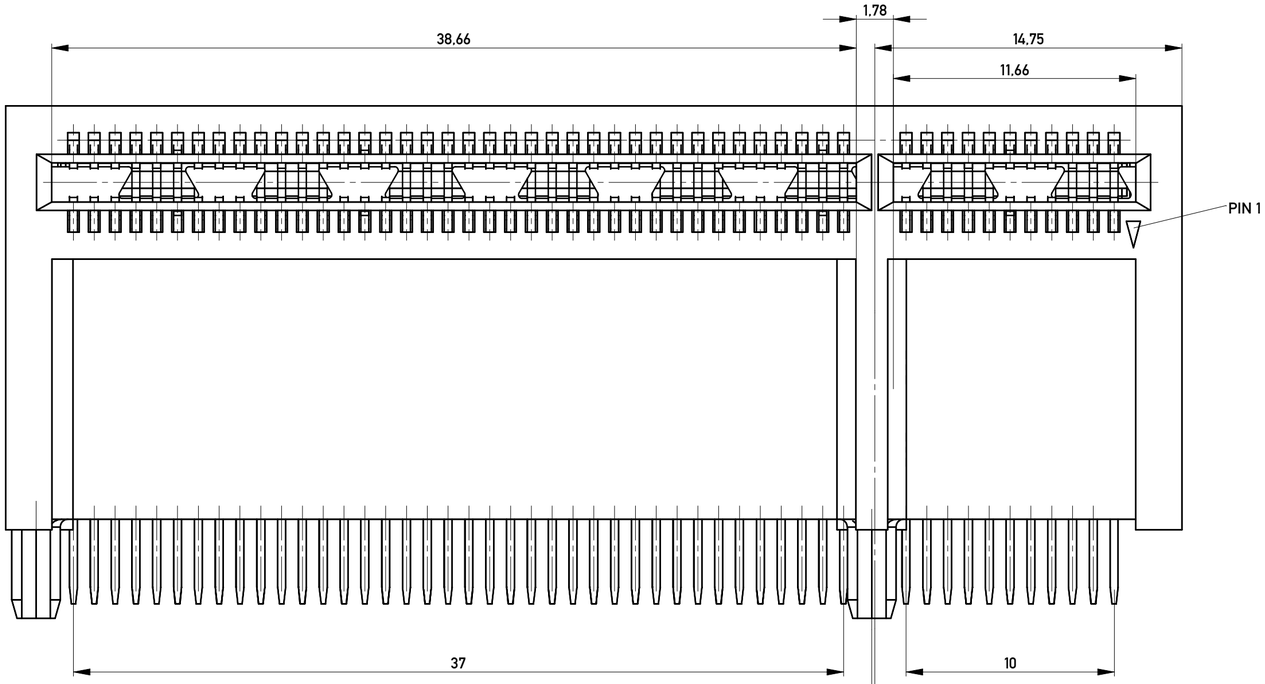
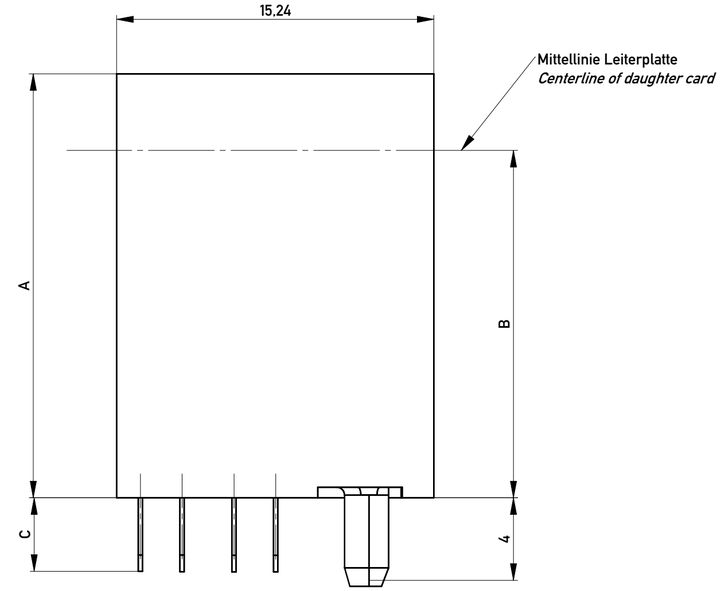
Detail contact area

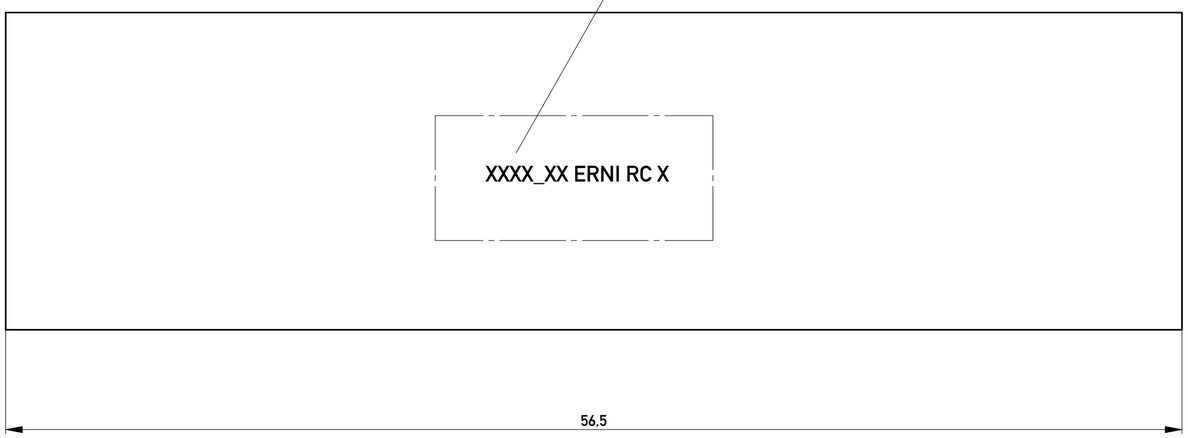




Offset von Führungssteg zu Referenzzapfen 0,15
Offset from guiding bar to reference peg



Datum
Date code (see notes)



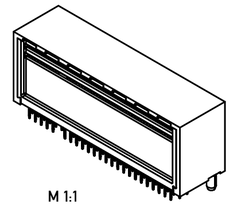
NOTES :

Material: LCP GF 30 schwarz
Material: LCP GF 30 black

Galvanik: min. 1,27 µm Unternickelung
über gesamten PIN - Bereich
min. 0,8 µm Au (30 µinch Au) im Steckbereich
Gold - Flash im Lötbereich
Plating: min. 1,27 µm Ni entire contact
min. 0,8 µm Au (30 µinch) in contact area
Gold - Flash plating on contact tails

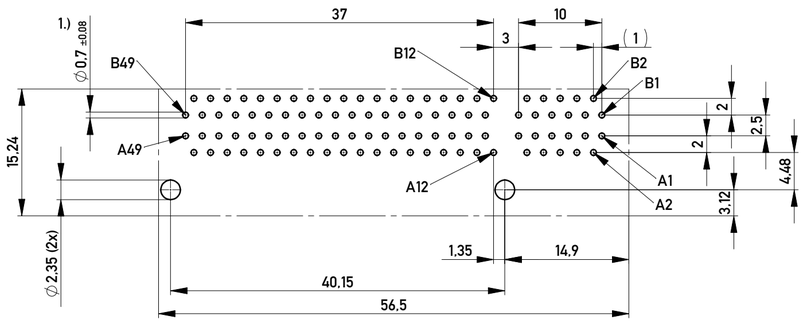
1.) Fertiglochdurchmesser
finished viadiameter (PTH)

Package: Tray (20 pcs.)

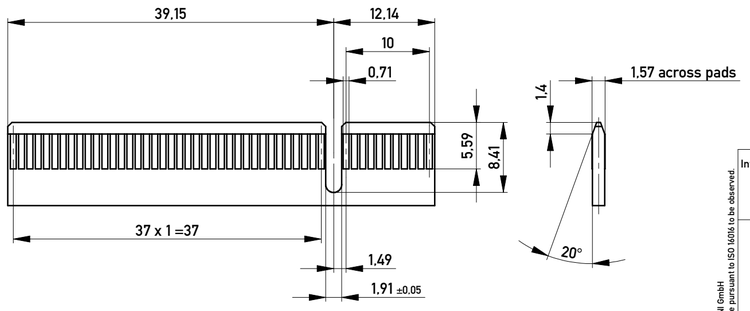


M 1:1

Lochbild für Leiterplatte (Bestückungsseite)
Board hole pattern (component mounting side)



daughter card layout



Layout proposal is in accordance with the PCI Express spezification

20,3	16,69	2,54
Maß "A" *Dim "A"*	Maß "B" *Dim "B"*	Maß "C" *Dim "C"*

Information:

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Tolerances

All Dimensions in mm

Subject to modification without prior notice.
Drawing will not be updated.

www.ERNI.com

Scale 5:1

Designation
Abgew. PCI Express STV 98pol.
RT. Angle PCI Express 98 pins

100201350001

K

A2

Class PCIEXP

Index		Date
c		04.11.2011

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